



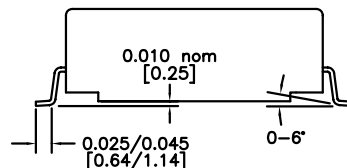
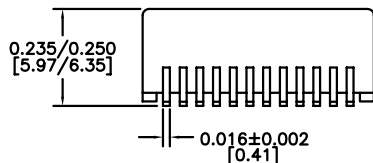
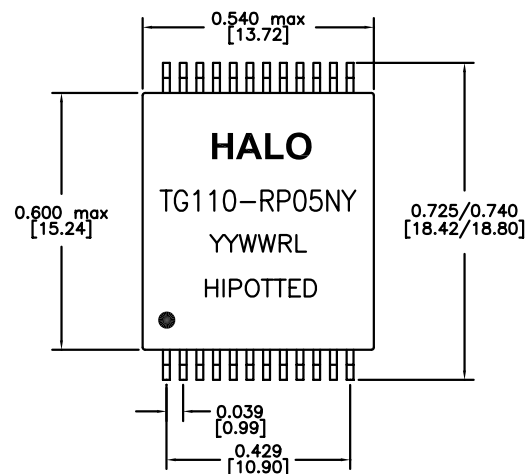
PART NO. : TG110-RP05NYRL

24PIN 0.039" LEAD PITCH SMT PACKAGE
FAST ETHERNET 10/100BASE-TX MAGNETICS
COMPLIANT WITH IEEE802.3af STANDARD
350mA CURRENT CARRYING CAPACITY
ON LINE SIDE FOR PoE APPLICATIONS

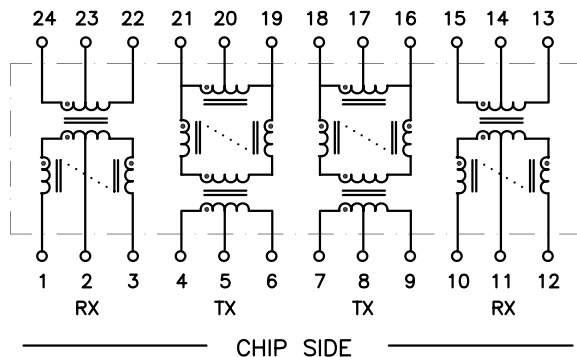
RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



ELECTRICAL SPECIFICATIONS @25° C

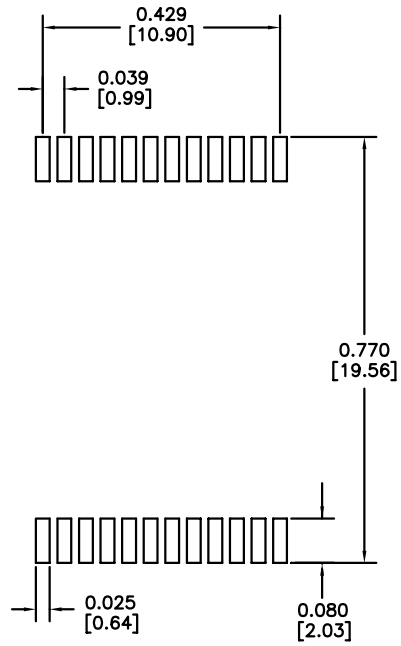
URNS RATIO	1CT:1CT±2%
OCL (100KHz,0.1Vrms,8mA) P4-6,P7-9,P15-13,P24-22	350µH min
DCR P4-6,P7-9,P15-13,P24-22	1.0Ω max
INSERTION LOSS 0.1-100MHz	-1.1dB max
RETURN LOSS 0.5-30MHz 40MHz 50MHz 60-80MHz	-18dB min -16dB min -13dB min -12dB min
CMR 0.1-100MHz	-40dB typ
CROSSTALK 0.1-100MHz	-40dB typ
ISOLATION	1,500Vrms



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST ETHERNET, PoE		DRAWN	PETER LU	4/27/05	A	FIRST ISSUE
PART NO.	TG110-RP05NYRL		CHECKED	LEI KEONG	5/6/06	B	PROD. RELEASE
SCALE	NONE	PAGE	1 OF 2		APPROVED	PETER LU	5/6/06
			FILE	RP05NYRL.DWG			



RECOMMENDED SOLDER PAD DIMENSIONS
 DIMENSIONS: Inch [mm]

HALO/PBL	TITLE ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR FAST ETHERNET, PoE		DRAWN PETER LU		4/27/05	A	FIRST ISSUE	4/27/05
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	PART NO. TG110-RP05NYRL		CHECKED LEI KEONG		5/6/06	B	PROD. RELEASE	5/6/06
	SCALE NONE	PAGE 2 OF 2	APPROVED PETER LU		5/6/06			
			FILE RP05NYRL.DWG					